

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
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Assignment ID: PATI895115

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	Patent Security Agreement
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Lemko Corporation	02/27/2025
<b>RECEIVING PARTY DATA</b>	
<b>Company Name:</b>	Piccadilly Patent Funding LLC, as Security Holder
<b>Street Address:</b>	520 Madison Avenue
<b>Internal Address:</b>	30th Floor
<b>City:</b>	New York
<b>State/Country:</b>	NEW YORK
<b>Postal Code:</b>	10022
<b>PROPERTY NUMBERS Total: 32</b>	
<b>Property Type</b>	<b>Number</b>
Patent Number:	7486967
Patent Number:	7539158
Patent Number:	7548763
Patent Number:	7653414
Patent Number:	7840230
Patent Number:	7855988
Patent Number:	7856233
Patent Number:	7979066
Patent Number:	8036158
Patent Number:	8046420
Patent Number:	8089920
Patent Number:	8107409
Patent Number:	8224322
Patent Number:	8310990
Patent Number:	8326286
Patent Number:	8340667
Patent Number:	8359029
Patent Number:	8600406
Patent Number:	8676197

Property Type	Number
Patent Number:	8688111
Patent Number:	8693955
Patent Number:	8706105
Patent Number:	8744435
Patent Number:	8780804
Patent Number:	9191980
Patent Number:	9198020
Patent Number:	9215098
Patent Number:	9253622
Patent Number:	9332478
Patent Number:	9515770
Patent Number:	9755931
Patent Number:	10547530

#### CORRESPONDENCE DATA

**Fax Number:**

*Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.*

**Phone:** 2028357507

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**Address Line 2:** Suite 1100

**Address Line 4:** Washington, DISTRICT OF COLUMBIA 20006

<b>ATTORNEY DOCKET NUMBER:</b>	45831.00006
<b>NAME OF SUBMITTER:</b>	Mr. JAVIER RAMOS
<b>SIGNATURE:</b>	/Mr. JAVIER RAMOS/
<b>DATE SIGNED:</b>	03/25/2025

**Total Attachments: 4**

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source=Patent Security Agreement - Lemko Corporation#page4.tiff

## PATENT SECURITY AGREEMENT

This PATENT SECURITY AGREEMENT (this “Agreement”) is entered into as of February 27, 2025 (this “Agreement”), by and between Lemko Corporation (“Grantor”) in favor of Piccadilly Patent Funding LLC (“Security Holder”).

Reference is made to that certain funding agreement, dated as of February 27, 2025, among Grantor, Security Holder and certain other parties (as amended, restated, amended and restated, supplemented or otherwise modified from time to time, the “Security Agreement”). Consistent with the requirements set forth in the Security Agreement, the parties hereto agree as follows:

SECTION 1. *Terms.* Capitalized terms used in this Agreement and not otherwise defined herein have the meanings specified in the Security Agreement, as applicable, as in effect on the date hereof.

SECTION 2. *Grant of Security Interest.* To secure Security Holder’s rights pursuant to the Security Agreement and as security for the obligations of Grantor under the Security Agreement, Grantor did and hereby does convey, assign, pledge and grant to Security Holder a first priority security interest in all of Grantor’s right, title and interest in, to and under the Collateral (as defined in the Security Agreement), including the patents and patent applications listed in Schedule I hereto.

SECTION 3. *Security Agreement.* The security interests granted to the Security Holder herein are granted in furtherance, and not in limitation of, the security interests granted to the Security Holder pursuant to the Security Agreement. Grantor hereby acknowledges and affirms that the rights and remedies of the Security Holder with respect to the Collateral are more fully set forth in the Security Agreement, the terms and provisions of which are hereby incorporated herein by reference as if fully set forth herein. In the event of any conflict between the terms of this Agreement and the Security Agreement, the terms of the Security Agreement shall govern.

SECTION 4. *Termination or Release.* In connection with any termination or release pursuant to the Security Agreement, the Security Holder shall promptly execute and deliver to Grantor, at Grantor’s expense, such documents that Grantor shall reasonably request to evidence and/or effectuate the termination or release of the security interest granted herein.

SECTION 5. *Governing Law.* This Agreement, and any claim, controversy or dispute arising under or related to this Agreement, whether in tort, contract (at law or in equity) or otherwise, shall be governed by, and construed and interpreted in accordance with, the laws of the state of Delaware.

SECTION 6. *Counterparts.* This Agreement may be executed in counterparts (and by different parties hereto on different counterparts), each of which shall constitute an original, but all of which when taken together shall constitute a single contract. Delivery of an executed counterpart of a signature page of this Agreement by facsimile or by email as a “.pdf” or “.tif” attachment or other electronic transmission shall be effective as delivery of a manually executed counterpart of this Agreement.

[Signature Pages Follow]

IN WITNESS WHEREOF, Grantor has duly executed this Agreement as of the day and year first above written.

**Lemko Corporation**

By: **Shaowei Pan** Digitally signed by Shaowei Pan  
Date: 2025.02.14 15:46:25 -06'00'

Name: Dr. Shaowei Pan

Title: Acting CEO

## **SCHEDULE I**

### **PATENTS**

U.S. Patent No. 7,486,967; System, method, and device for providing communications using a distributed mobile architecture; Issued on February 3, 2009

U.S. Patent No. 7,539,158; System, method and device for providing communications using a distributed mobile architecture Issued on May 26, 2009

U.S. Patent No. 7,548,763; System, method, and device for providing communications using a distributed mobile architecture; Issued on June 16, 2009

U.S. Patent No. 7,653,414; System, method, and device for providing communications using a distributed mobile architecture; Issued on January 26, 2010

U.S. Patent No. 7,840,230; Communications using a distributed mobile architecture; Issued on November 23, 2010

U.S. Patent No. 7,855,988; System, method, and device for routing calls using a distributed mobile architecture; Issued on December 21, 2010

U.S. Patent No. 7,856,233; System, method, and device for providing communications using a distributed mobile architecture; Issued on December 21, 2010

U.S. Patent No. 7,979,066; Multiple IMSI connections; Issued on July 12, 2011

U.S. Patent No. 8,036,158; System, method, and device for providing communications using a distributed mobile architecture; Issued on October 11, 2011

U.S. Patent No. 8,046,420; System and method to control wireless communications; Issued on October 25, 2011

U.S. Patent No. 8,089,920; Communications using a distributed mobile architecture; Issued on January 3, 2012

U.S. Patent No. 8,107,409; OAMP for distributed mobile architecture; Issued on January 31, 2012

U.S. Patent No. 8,224,322; 8,224,322; Issued on July 17, 2012

U.S. Patent No. 8,310,990; System, method, and device for routing calls using a distributed mobile architecture; Issued on November 13, 2012

U.S. Patent No. 8,326,286; Multiple IMSI numbers; Issued on December 4, 2012

U.S. Patent No. 8,340,667; System and method to control wireless communications; Issued on December 25, 2012

Schedule I

U.S. Patent No. 8,359,029; System, method, and device for providing communications using a distributed mobile architecture; Issued on January 22, 2013

U.S. Patent No. 8,600,406; System and method for location determination for mobile clients; Issued on December 3, 2013

U.S. Patent No. 8,676,197; System, method, and device to control wireless communications; Issued on March 18, 2014

U.S. Patent No. 8,688,111; System, method, and device for providing communications using a distributed mobile architecture; Issued on April 1, 2014

U.S. Patent No. 8,693,955; Method and apparatus for determining the location of a node in a wireless system; Issued on April 8, 2014

U.S. Patent No. 8,706,105; Fault tolerant distributed mobile architecture; Issued on April 22, 2014

U.S. Patent No. 8,744,435; Multiple IMSI numbers; Issued on June 3, 2014

U.S. Patent No. 8,780,804; Providing communications using a distributed mobile architecture; Issued on July 15, 2014

U.S. Patent No. 9,191,980; System and method to control wireless communications; Issued on November 17, 2015

U.S. Patent No. 9,198,020; OAMP for distributed mobile architecture; Issued on November 24, 2015

U.S. Patent No. 9,215,098; System and method to control wireless communications; Issued on December 15, 2015

U.S. Patent No. 9,253,622; Roaming mobile subscriber registration in a distributed mobile architecture; Issued on February 2, 2016

U.S. Patent No. 9,332,478; System, method, and device for routing calls using a distributed mobile architecture; Issued on May 3, 2016

U.S. Patent No. 9,515,770; System, method, and device to control wireless communications; Issued on December 6, 2016

U.S. Patent No. 9,755,931; Fault tolerant distributed mobile architecture; Issued on September 5, 2017

U.S. Patent No. 10,547,530; Fault tolerant distributed mobile architecture; Issued on January 28, 2020

Schedule I